

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (Canceled).

Claim 2 (Previously Presented): The multi-layer printed wiring board according to claim 16, wherein the ground through hole in the core substrate including two or more ground through holes and the power through hole including two or more power through holes, such that the ground through holes and the power through holes are disposed in a grid formation or in a staggered formation at adjacent positions.

Claim 3 (Canceled).

Claim 4 (Previously Presented): The multi-layer printed wiring board according to claim 16, wherein the diameter of the ground through hole is 50 to 500 μm and the diameter of the power through hole is 50 to 500 μm .

Claim 5 (Previously Presented): The multi-layer printed wiring board according to claim 16, wherein at least one through hole of the ground through holes and the power through holes comprises two or more through holes in a stack structure through all layers of the multi-layer printed wiring board up to an outermost layer.

Claim 6 (Previously Presented): The multi-layer printed wiring board according to any one of claims 16, 2 or 5 wherein the ground through hole and the power through hole are disposed just below an IC chip.

Claim 7 (Previously Presented): The multi-layer printed wiring board according to claim 16 or 2 wherein the thickness of conductive layer on the core substrate is larger than the thickness of the conductive layer on the interlayer insulating layer.

Claim 8 (Currently Amended): The multi-layer printed wiring board according to claim 16 or 2 wherein assuming that the thickness of the conductive layer on the core substrate is α_1

[[1]] and the thickness of the conductive layer on the interlayer insulating layer is α_2 , $\alpha_2 < \alpha_1 \leq 40\alpha_2$.

Claim 9 (Original): The multi-layer printed wiring board according to claim 8 wherein the α_1 is in a relation of $1.2\alpha_2 \leq \alpha_1 \leq 40\alpha_2$.

Claim 10 (Previously Presented): The multi-layer printed wiring board according to claim 7, wherein each conductive layer of the core substrate is conductive layer for power layer or conductive layer for grounding.

Claim 11 (Previously Presented): The multi-layer printed wiring board according to claim 16, wherein a capacitor is mounted on the surface thereof.

Claim 12 (Canceled).

Claim 13 (Previously Presented): The multi-layer printed wiring board according to claim 16 or 2 wherein the core substrate is a multi-layer core substrate composed of three layers.

Claim 14 (Canceled).

Claim 15 (Previously Presented): The multi-layer printed wiring board according to claim 13 wherein the conductive layer in the inner layer of the core substrate is composed of two or more layers.

Claim 16 (Previously Presented): A multi-layer printed wiring board comprising:
a core substrate having a plurality of through holes therein, the through holes in the core substrate being disposed so that a ground through hole and a power through hole adjoin each other, wherein a distance between the ground through hole and the power through hole is in a range of 60 to 550 μm ;

an interlayer insulating layer formed on the core substrate;

a conductive layer formed on the interlayer insulating layer; and

a plurality of via holes provided in the insulating layer and configured to provide electrical connection between the conductive layer and through holes, wherein:

the core substrate is a multi-layer core substrate composed of three or more layers and including a thick conductive layer as an inner layer, and a conductive layer as a surface layer,

the conductive layer of each inner layer of the core substrate and the conductive layer of each surface layer are a conductive layer for power layer or a conductive layer for grounding, and

the core substrate is so constructed that the thick conductive layer as an inner layer comprises first and second thick conductive layers formed on respective sides of a metallic plate which is electrically insulated by a resin layer, and the conductive layer as a surface layer is formed outside the conductive layer as an inner layer interposed by a resin layer.

Claim 17 (Previously Presented): The multi-layer printed wiring board according to claim 16, wherein the core substrate is so constructed that the thick conductive layer is disposed as the inner layer and a thin conductive layer is formed as the surface layer disposed on a surface side.